CLAIMS

WHAT IS CLAIMED IS:

1. A device comprising:

a fiber optic bundle having a termination block;

an array waveguide having channels internally, the array waveguide positioned adjacent to the termination block; and

two pins each partially extending into both the termination block and the array waveguide.

2. The device of claim 1, wherein the termination block comprises two retainers having etched grooves in them, and the two pins extend into holes formed by placing the two etched substrates together.

3. The device of claim 2, wherein the array waveguide has two holes formed by an etch process.

4. The device of claim 2 further comprising

a gel dispensed between the termination block and the array waveguide.

5. The device of claim 4, wherein the gel has an index of refraction substantially similar to that of the channels of the array waveguide.

6. A method of aligning a fiber optic bundle with an array waveguide comprising:

inserting pins into holes formed in both the fiber optic bundle and the array waveguide; and

pressing the fiber optic bundle and the array waveguide together so that the pins extend into both the fiber optic bundle and the array waveguide.

7. The method of claim 6 further comprising:

finely aligning optical fibers in the fiber optic bundle with channels of the array waveguide.

8. The method of claim 7 further comprising:

applying an epoxy to bond the fiber optic bundle to the array waveguide.

9. The method of claim 8 further comprising:

dispensing an optical gel between the fiber optic bundle and the array waveguide.

10. The method of claim 9, wherein the optical gel has an index of refraction substantially similar to channels in the array waveguide.

11. The method of claim 10 further comprising:

curing the epoxy while maintaining alignment between the optical fibers and the channels of the array waveguide.

12. A method of aligning a fiber optic bundle with an array waveguide comprising:

inserting two pins into holes formed in an end of the fiber optic bundle;

inserting opposite ends of the two pins into the array waveguide; and

pressing the fiber optic bundle and the array waveguide together.

13. The method of claim 12 further comprising:

adjusting the fiber optic bundle and the array waveguide to improve photonic coupling between optical fibers of the fiber optic bundle and channels of the array waveguide.

14. The method of claim 13 further comprising:

dispensing an epoxy between the fiber optic bundle and the array waveguide.

15. The method of claim 14, wherein the dispensing the epoxy is performed by dispensing an epoxy having an index of refraction substantially similar to the channels of the array waveguide.